



Date Created: 4/19/2004
Date Issued: 4/28/2004
PCN # 20040611-A

DESIGN/PROCESS CHANGE NOTIFICATION -- FINAL

This is the first revision of the PCN 20040611 to issue Final PCN
This is to inform you that a design and/or process change will be made to the
following product(s). This notification is for your information and concurrence.

If you require data or samples to qualify this change, please contact **Fairchild Semiconductor within 30 days of receipt of this notification.**

If you have any questions concerning this change, please contact:

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PCN Type: Alternate Assembly Site Location/Qualification

Effectivity

Expected 1st Device Shipment Date: 5/28/2004
Earliest Year/Work Week of Changed Product: 0422
(Note: Package marking may differ from this format)

Product ID (Description):

FSD210, FSD200 of 7pin-DIP.
FSD210H, FSDH0165, FSDH0165D, FSDH0165G of 8pin-DIPH

Description of Change:

Fairchild Semiconductor Corporation's manufacturing facility in Penang, Malaysia will be qualified as an alternative assembly and test site for Fairchild's 7-pin DIP and 8-pin DIPH packages. These packages will be qualified for production in Penang with Pb-free plating. This product will also continue to be assembled and tested by the currently qualified supplier, SZEC in China. As previously noted in PCN# 20032701, SZEC will also be converting to Pb-free plating. The current schedule is such that at the time these products are approved for shipment from Penang, there will be no differences in assembly materials, plating or packing materials, except marking method on package and tube dimensions.

	Width (top-side)	Width (bottom-side)	Height	Material thickness	Tube Length	Package Marking
SZEC(From)	9.00mm	12.90mm	11.10m m	0.5mm	500.0mm	Laser Marking
Panang(To)	10.65mm	13.97mm	11.43m m	0.5mm	501.0mm	Ink Marking

Effect of Change:

This change will not affect any electrical characteristics & reliability. The change will enlarge the production capacity to meet customer's needs. There is no difference in assembly materials or packing materials. except marking method on package and tube dimensions. Under Fairchild's control, the same program will be applied to test the products from the Penang Location

Qualification:

The qualification plan is intended to meet our criteria for qualifying an alternate assembly & test site, the overall quality and reliability of our products.

Qual/REL Plan Numbers

Additional Qualification Data

* The FSD210(7DIP) is a representative device for this reliability test results.

items	Test Conditions	Sample size	Test Hour	Result
HTRB	Vdd=560V, Ta=125°C	77 ea	1000hr	0/77ea
HTOL	Vdd=100V, Vcc=17V, Vstr=400V, Ta=125°C	77 ea	1000hr	0/77ea
HTOL (J-FET)	Vstr=560V, Ta=125°C	77 ea	1000hr	0/77ea
HTSL	Ta= 150°C	77 ea	1000hr	0/77ea
THBT	85°C/ 85%, Vcc= 15V->10V	77 ea	1000hr	0/77ea
TMCL	-65°C ~ +150°C	77 ea	500cyle	0/77ea
ACLV	Ta=121°C, RH=100%, Pressure=15 PSIG	77 ea	96hr	0/77ea
Dynamic	Vin=220Vac	30 ea		0/30ea

* The FSD210H(8DIPH) is a representative device for this reliability test results.

items	Test Conditions	Sample size	Test Hour	Result
HTRB	Vdd=560V, Ta=125°C	77 ea	1000hr	0/77ea
HTOL	Vdd=100V, Vcc=17V, Vstr=400V, Ta=125°C	77 ea	1000hr	0/77ea
HTSL	Ta= 150°C	77 ea	1000hr	0/77ea
THBT	85°C/ 85%, Vcc= 15V->10V	77 ea	1000hr	0/77ea
TMCL	-65°C ~ +150°C	77 ea	500cyle	0/77ea
ACLV	Ta=121°C, RH=100%, Pressure=15 PSIG	77 ea	96hr	0/77ea

Affected FSIDs

FSD200
FSDH0165

FSD210
FSDH0165D

FSD210H
FSDH0165G